- Power-On Reset Generator
- Automatic Reset Generation After Voltage Drop
- Precision Voltage Sensor
- Temperature-Compensated Voltage Reference
- Programmable Delay Time by External Capacitor
- Supply Voltage Range . . . 2 V to 6 V
- Defined RESET Output from V<sub>DD</sub> ≥1 V
- Power-Down Control Support for Static RAM With Battery Backup
- Maximum Supply Current of 16 μA
- Power Saving Totem-Pole Outputs
- Temperature Range . . . Up to −55°C to 125°C



The TLC77xx family of micropower supply voltage supervisors provide reset control, primarily in microcomputer and microprocessor systems.

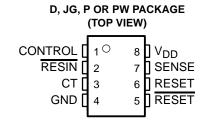
During power-on,  $\overline{RESET}$  is asserted when  $V_{DD}$  reaches 1 V. After minimum  $V_{DD}$  ( $\geq$  2 V) is established, the circuit monitors SENSE voltage and keeps the reset outputs active as long as SENSE voltage ( $V_{I(SENSE)}$ ) remains below the threshold voltage. An internal timer delays return of the output to the inactive state to ensure proper system reset. The delay time,  $t_d$ , is determined by an external capacitor:

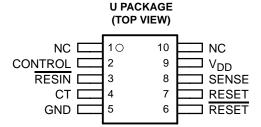
$$t_d = 2.1 \times 10^4 \times C_T$$

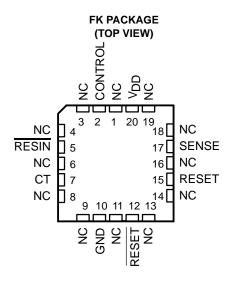
Where

C<sub>⊤</sub> is in farads

td is in seconds







Except for the TLC7701, which can be customized with two external resistors, each supervisor has a fixed SENSE threshold voltage set by an internal voltage divider. When SENSE voltage drops below the threshold voltage, the outputs become active and stay in that state until SENSE voltage returns above threshold voltage and the delay time,  $t_{\rm cl}$ , has expired.



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#### description (continued)

In addition to the power-on-reset and undervoltage-supervisor function, the TLC77xx adds power-down control support for static RAM. When CONTROL is tied to GND, RESET will act as active high. The voltage monitor contains additional logic intended for control of static memories with battery backup during power failure. By driving the chip select (CS) of the memory circuit with the RESET output of the TLC77xx and with the CONTROL driven by the memory bank select signal (CSH1) of the microprocessor (see Figure 10), the memory circuit is automatically disabled during a power loss. (In this application the TLC77xx power has to be supplied by the battery.)

The TLC77xxI is characterized for operation over a temperature range of  $-40^{\circ}$ C to  $85^{\circ}$ C; the TLC77xxQ is characterized for operation over a temperature range of  $-40^{\circ}$ C to  $125^{\circ}$ C; and the TLC77xxM is characterized for operation over the full Military temperature range of  $-55^{\circ}$ C to  $125^{\circ}$ C.

#### **AVAILABLE OPTIONS**

			PACKAGED DEVICES								
TA	THRESHOLD VOLTAGE (V)	SMALL OUTLINE (D)†	CHIP CARRIER (FK)	CERAMIC DIP (JG)	CERAMIC DUAL FLATPACK (U)	PLASTIC DIP (P)	THIN SHRINK SMALL OUTLINE (PW)‡				
	1.1	TLC7701ID	_		_	TLC7701IP	TLC7701IPW				
-40°C	2.25	TLC7725ID	_			TLC7725IP	TLC7725IPW				
to	2.63	TLC7703ID	_	_	_	TLC7703IP	TLC7703IPW				
85°C	2.93	TLC7733ID	_	_	_	TLC7733IP	TLC7733IPW				
	4.55	TLC7705ID	_	_	_	TLC7705IP	TLC7705IPW				
	1.1	TLC7701QD	_	_	_	TLC7701QP	TLC7701QPW				
-40°C	2.25	TLC7725QD	_	_	_	TLC7725QP	TLC7725QPW				
to	2.63	TLC7703QD	_	_	_	TLC7703QP	TLC7703QPW				
125°C	2.93	TLC7733QD	_	_	_	TLC7733QP	TLC7733QPW				
	4.55	TLC7705QD	_	_	_	TLC7705QP	TLC7705QPW				
−55°C to	2.93	_	TLC7733MFK	TLC7733MJG	_	_	_				
to 125°C	4.55	_	TLC7705MFK	TLC7705MJG	TLC7705MU	_	_				

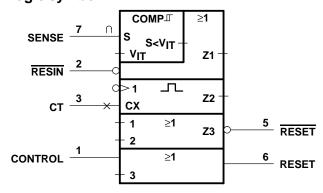
<sup>†</sup> The D package is available taped and reeled. Add the suffix R to the device type when ordering (e.g., TLC7705QDR).

#### **FUNCTION TABLE**

CONTROL	RESIN	V <sub>I</sub> (SENSE)>V <sub>IT+</sub>	RESET	RESET
L	L	False	Н	L
L	L	True	Н	L
L	Н	False	Н	L
L	Н	True	L§	н§
Н	L	False	Н	L
Н	L	True	Н	L
Н	Н	False	Н	L
Н	Н	True	Н	Н§

<sup>§</sup> RESET and RESET states shown are valid for t > td.

#### logic symbol¶

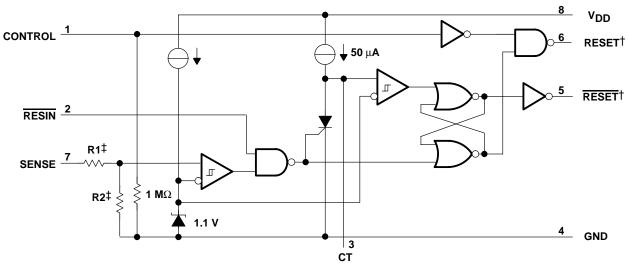


<sup>¶</sup> This symbol is in accordance with ANSI/IEEE Std 91–1984 and IEC Publication 617-12.



<sup>&</sup>lt;sup>‡</sup>The PW package is only available left-end taped and reeled (indicated by the LE suffix on the device type; e.g., TLC7705QPWLE).

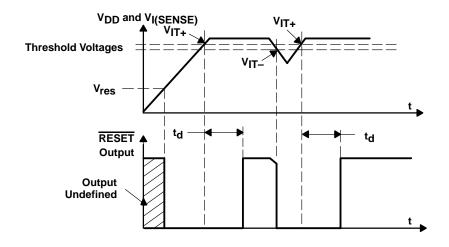
#### functional block diagram



- †Outputs are totem-pole configuration. External pullup or pulldown resistors are not required.
- ‡ Nominal values:

	R1 (Typ)	R2 (Typ)
TLC7701	0	8
TLC7725	600 kΩ	600 kΩ
TLC7703	698 kΩ	502 kΩ
TLC7733	750 kΩ	450 kΩ
TLC7705	910 kΩ	290 kΩ

### timing diagram



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### absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage, V <sub>DD</sub> (see Note 1)	
Input voltage range, CONTROL, RESIN, SENSE (see Note 1)	0.3 V to 7 V
Maximum low output current, I <sub>OL</sub>	10 mA
Maximum high output current, IOH	–10 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{DD}$ )	±10 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>DD</sub> )	±10 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T <sub>A</sub> : TL77xxI	–40°C to 85°C
TL77xxQ	–40°C to 125°C
TL77xxM	–55°C to 125°C
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to GND.

#### **DISSIPATION RATING TABLE**

PACKAGE	$T_{\mbox{A}} \le 25^{\circ}\mbox{C}$ POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 85°C POWER RATING	T <sub>A</sub> = 125°C POWER RATING
D	725 mW	5.8 mW/°C	377 mW	145 mW
FK	1375 mW	11.0 mW/°C	715 mW	275 mW
JG	1050 mW	8.4 mW/°C	546 mW	210 mW
Р	1000 mW	8.0 mW/°C	520 mW	200 mW
PW	525 mW	4.2 mW/°C	273 mW	105 mW
U	700 mW	5.5 mW/°C	370 mW	150 mW

#### recommended operating conditions at specified temperature range

			MIN	MAX	UNIT
Supply voltage, V <sub>DD</sub>			2	6	V
Input voltage, V <sub>I</sub>			0	V	
High-level input voltage at RESIN and CONTR	OL <sup>‡</sup> , V <sub>IH</sub>		0.7×V <sub>DD</sub>	V	
Low-level input voltage at RESIN and CONTR	OL‡, V <sub>IL</sub>			0.2×V <sub>DD</sub>	V
High-level output current, IOH	V>27V			-2	mA
Low-level output current, IOL	TROL $^{\ddagger}$ , V <sub>IL</sub> $V_{DD} \ge 2.7 \text{ V}$		2	mA	
Input transition rise and fall rate at RESIN and	CONTROL, Δt/ΔV			100	ns/V
Operating free-air temperature range, TA	TLC77xxI		-40	85	°C
Operating nee-all temperature range, 1A	TLC77xxQ		-40	V <sub>DD</sub> 0 0.2×V <sub>DD</sub> -2 2 100	C
Operating free-air temperature range, TA	TLC77xxM		-55	125	°C

 $<sup>\</sup>overline{\ddagger}$  To ensure a low supply current, V<sub>IL</sub> should be kept < 0.3 V and V<sub>IH</sub> > V<sub>DD</sub> -0.3 V.



## electrical characteristics over recommended operating conditions (see Note 2) (unless otherwise noted)

					1	TLC77xx		
	PARAMETE	ER .		TEST CONDITIONS	MIN	түр†	MAX	UNIT
				V <sub>DD</sub> = 2 V	1.8			
M	High lavel autout valtage	I <sub>OH</sub> = -20 μ	Α	V <sub>DD</sub> = 2.7 V	2.5			V
VOH	High-level output voltage			V <sub>DD</sub> = 4.5 V	4.3			V
		$I_{OH} = -2 \text{ m/s}$	A	V <sub>DD</sub> = 4.5 V	3.7			
				V <sub>DD</sub> = 2 V			0.2	
\/a.	Low-level output voltage	I <sub>OL</sub> = 20 μA		V <sub>DD</sub> = 2.7 V			0.2	V
VOL	Low-level output voltage			V <sub>DD</sub> = 4.5 V			0.2	V
		$I_{OL} = 2 \text{ mA}$		V <sub>DD</sub> = 4.5 V			0.5	
			TLC7701		1.04	1.1	1.16	
			TLC7725		2.18	2.25	2.32	
$V_{IT-}$	Negative-going input thresh SENSE (see Note 3)	old voltage,	TLC7703	$V_{DD} = 2 V \text{ to } 6 V$	2.56	2.63	2.70	V
	02.102 (000 110.0 0)		TLC7733		2.86	2.93	3	
			TLC7705		4.47	4.55	4.63	
	Hysteresis voltage, SENSE TLC7 TLC7		TLC7701	$V_{DD} = 2 V \text{ to } 6 V$		30		mV
			TLC7725					
$V_{hys}$			TLC7703,	V <sub>DD</sub> = 2 V to 6 V		70		mV
			TLC7733,					IIIV
			TLC7705					
V <sub>res</sub>	Power-up reset voltage‡			I <sub>OL</sub> = 20 μA			1	V
		RESIN		V <sub>I</sub> = 0 V to V <sub>DD</sub>			2	
1.	Lament accomment	CONTROL		$V_I = V_{DD}$		7	15	^
lı	Input current	SENSE		V <sub>I</sub> = 5 V		5	10	μΑ
		SENSE, TLC	7701 only	V <sub>I</sub> = 5 V			2	
I <sub>DD</sub>	Supply current		$\overline{\text{RESIN}} = \text{V}_{\text{DD}},$ $\text{SENSE} = \text{V}_{\text{DD}} \ge \text{V}_{\text{IT}} \text{max} + 0.2 \text{ V}$ $\text{CONTROL} = 0 \text{ V},  \text{Outputs open}$		9	16	μΑ	
I <sub>DD(d)</sub>	DD(d) Supply current during t <sub>d</sub>			$\begin{split} & \frac{V_{DD} = 5 \text{ V,}}{\text{RESIN}} = V_{DD}, & \text{SENSE} = V_{DD}, \\ & \text{CONTROL} = 0 \text{ V,} & \text{Outputs open} \end{split}$		120	150	μΑ
Cl	Input capacitance, SENSE			$V_I = 0 V \text{ to } V_{DD}$		50		pF

<sup>†</sup> Typical values apply at  $T_A = 25$ °C.



<sup>&</sup>lt;sup>‡</sup>The lowest supply voltage at which RESET becomes active. The symbol V<sub>res</sub> is not currently listed within EIA or JEDEC standards for semiconductor symbology. Rise time of V<sub>DD</sub> ≥ 15 μs/V.

NOTES: 2. All characteristics are measured with  $C_T = 0.1 \mu F$ .

<sup>3.</sup> To ensure best stability of the threshold voltage, a bypass capacitor (ceramic, 0.1 µF) should be connected near the supply terminals.

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# electrical characteristics over recommended operating conditions (see Note 2) (unless otherwise noted)

	545445				ONDITIONS.	T	LC77xxN	1	
	PARAME	IEK		l lesi c	ONDITIONS	MIN	TYP <sup>†</sup>	MAX	UNIT
				V== - 2 V	T <sub>A</sub> = 25°C	1.8			
				$V_{DD} = 2 V$ ,	$T_A = -55^{\circ}C \text{ to } 125^{\circ}C$	1.7			
		J 00	Λ	V 0.7.V	T <sub>A</sub> = 25°C	2.5			
\ <sub>\\-</sub>	High-level output	I <sub>OH</sub> = -20 μ	4	V <sub>DD</sub> = 2.7 V	$T_A = -55^{\circ}C$ to $125^{\circ}C$	2.3			V
VOH	voltage			V 45V	T <sub>A</sub> = 25°C	4.3			V
				V <sub>DD</sub> = 4.5 V	$T_A = -55^{\circ}C \text{ to } 125^{\circ}C$	4.2			
		Ja 2 m/		V== - 4 E V	T <sub>A</sub> = 25°C	3.7			
		$I_{OH} = -2 \text{ m/s}$	1	V <sub>DD</sub> = 4.5 V	$T_A = -55^{\circ}C \text{ to } 125^{\circ}C$	3.6			
				V <sub>DD</sub> = 2 V	T <sub>A</sub> = 25°C			0.2	
				VDD = 2 v	$T_A = -55^{\circ}C$ to $125^{\circ}C$			0.2	
		lo 20 A		V== - 2.7.V	T <sub>A</sub> = 25°C			0.2	
\ <sub>\\-</sub> .	Low-level output	I <sub>OL</sub> = 20 μA		$V_{DD} = 2.7 V$	$T_A = -55^{\circ}C$ to $125^{\circ}C$			0.2	,
VOL	voltage		V 45V	T <sub>A</sub> = 25°C			0.2	V	
				V <sub>DD</sub> = 4.5 V	$T_A = -55^{\circ}C \text{ to } 125^{\circ}C$				0.2
		I <sub>OL</sub> = 2 mA		V== 45V	T <sub>A</sub> = 25°C				0.5
				V <sub>DD</sub> = 4.5 V	$T_A = -55^{\circ}C \text{ to } 125^{\circ}C$				0.5
\/	Negative-going input thr	eshold	TLC7733	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\		2.86	2.93	3.1	V
VIT-	voltage, SENSE (see No	ote 3)	TLC7705	$V_{DD} = 2 \text{ V to } 6 \text{ V}$		4.3	4.5	4.8	V
V <sub>hys</sub>	Hysteresis voltage, SEN	ISE		$V_{DD} = 2 V \text{ to } 6 V$	V <sub>DD</sub> = 2 V to 6 V		70		mV
V <sub>res</sub>	Power-up reset voltage	ţ		I <sub>OL</sub> = 20 μA				1	V
		RESIN		$V_I = 0 V \text{ to } V_{DD}$				2	
l.		CONTROL		$V_I = V_{DD}$			7	15	^
'1	Input current	SENSE		V <sub>I</sub> = 5 V			5	10	μΑ
		SENSE, TLC	7701 only	V <sub>I</sub> = 5 V				2	
I <sub>DD</sub>	Supply current			RESIN = $V_{DD}$ , SENSE = $V_{DD} \ge V_{IT} max + 0.2 V$ CONTROL = 0 V, Outputs open			9	16	μА
וטטנא	Supply current during t <sub>d</sub>		TLC7733	$\frac{V_{CT} = 0}{RESIN} = V_{DD},$ CONTROL = 0 V,	V <sub>DD</sub> = 3.3 V			250	μΑ
IDD(d)	Supply current during to		TLC7705	SENSE = V <sub>DD</sub> , Outputs open	V <sub>DD</sub> = 5 V		120	150	μΛ
Cl	Input capacitance, SEN	SE		$V_I = 0 V \text{ to } V_{DD}$			50		pF

<sup>†</sup> Typical values apply at  $T_A = 25$ °C.



<sup>‡</sup> The lowest supply voltage at which  $\overline{\text{RESET}}$  becomes active. The symbol  $V_{\text{res}}$  is not currently listed within EIA or JEDEC standards for semiconductor symbology. Rise time of  $V_{\text{DD}} \ge 15~\mu\text{s/V}$ .

NOTES: 2. All characteristics are measured with  $C_T = 0.1 \mu F$ .

<sup>3.</sup> To ensure best stability of the threshold voltage, a bypass capacitor (ceramic, 0.1 µF) should be placed near the supply terminals.

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# switching characteristics at $V_{DD}$ = 5 V, $R_L$ = 2 k $\Omega$ , $C_L$ = 50 pF, $T_A$ = 25°C (unless otherwise noted)

		MEASUR	ED		Т			
	PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	MIN TYP MAX		UNIT
<sup>t</sup> d	Delay time	VI(SENSE) ≥ VIT+	RESET and RESET	$\overline{RESIN} = 0.7 \times V_{DD},$ $CONTROL = 0.2 \times V_{DD},$ $C_T = 100 \text{ nF},$ $T_A = \text{Full range},$ See timing diagram	1.1	2.1	4.2	ms
tPLH	Propagation delay time, low-to-high-level output		DECET	W			20	
<sup>t</sup> PHL	Propagation delay time, high-to-low-level output	CENCE	RESET	$V_{IH} = V_{IT+} max + 0.2 \text{ V},$ $V_{IL} = V_{IT-} min - 0.2 \text{ V},$ $\overline{RESIN} = 0.7 \times V_{DD},$				
<sup>t</sup> PLH	Propagation delay time, low-to-high-level output	SENSE	RESET	CONTROL = $0.2 \times V_{DD}$ , CT = NC†			5	μs
<sup>t</sup> PHL	Propagation delay time, high-to-low-level output	]	KESEI	C1 = NC1			20	
<sup>t</sup> PLH	Propagation delay time, low-to-high-level output			V. 0.7V			20	μs
tPHL	Propagation delay time, high-to-low-level output	DEON		$V_{IH} = 0.7 \times V_{DD}$ , $V_{IL} = 0.2 \times V_{DD}$ ,			40	
<sup>t</sup> PLH	Propagation delay time, low-to-high-level output	RESIN		SENSE = $V_{IT+}$ max + 0.2 V, CONTROL = 0.2 × $V_{DD}$ , CT = NC $\dagger$			45	ns
tPHL	Propagation delay time, high-to-low-level output		KESET	CT = NCT			20	μs
<sup>t</sup> PLH	Propagation delay time, low-to-high-level output	CONTROL	RESET	$V_{IH} = 0.7 \times V_{DD},$ $V_{IL} = 0.2 \times V_{DD},$ $SENSE = V_{IT+max} + 0.2 V,$			38	ns
<sup>t</sup> PHL	Propagation delay time, high-to-low-level output	CONTROL	KLOLI	$\frac{\text{BESIN}}{\text{RESIN}} = 0.7 \times \text{V}_{\text{DD}},$ $\text{CT} = \text{NC}^{\dagger}$			38	ns
	Low-level minimum pulse	SENSE		$V_{IH} = V_{IT+} max + 0.2 V,$ $V_{IL} = V_{IT-} min - 0.2 V,$	3			
	duration to switch RESET and RESET	RESIN		$V_{IL} = 0.2 \times V_{DD},$ $V_{IH} = 0.7 \times V_{DD}$	1			μs
t <sub>r</sub>	Rise time		RESET	10% to 90%		8		
t <sub>f</sub>	Fall time		and RESET	90% to 10%		4		ns/V

<sup>†</sup> NC = No capacitor, and includes up to 100-pF probe and jig capacitance.

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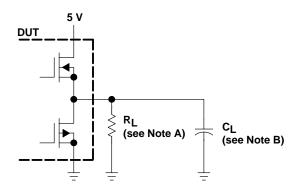
## switching characteristics at $V_{DD}$ = 5 V, $R_L$ = 2 $k\Omega$ , $C_L$ = 50 pF

		MEASURED				TLC77xxM				
	PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	TA	MIN	TYP	MAX	UNIT	
t <sub>d</sub>	Delay time	VI(SENSE) ≥ VIT+	RESET and RESET	RESIN = 2.7 V, CONTROL = 0.4 V, C <sub>T</sub> = 100 nF, See timing diagram	Full range	1.1	2.1	4.2	ms	
					25°C			20		
<b>.</b>	Propagation delay time, low-to-high-level	SENSE	RESET	$V_{IH} = V_{IT+} max + 0.2 V,$ $V_{IL} = V_{IT-} min - 0.2 V,$ RESIN = 2.7 V,	Full range			24	μs	
<sup>t</sup> PLH	output	SENSE		CONTROL = 0.4 V,	25°C			5		
	·		RESET	CT = NC†	Full range			7	μs	
					25°C			5		
<b>.</b>	Propagation delay time, high-to-low-level	SENSE	RESET	$V_{IH} = V_{IT+} max + 0.2 V,$ $V_{IL} = V_{IT-} min - 0.2 V,$ RESIN = 2.7 V,	Full range			7	μs	
tPHL	output	SENSE		CONTROL = 0.4 V,	25°C			20		
	·		RESET		Full range			24	μs	
	Propagation delay time, low-to-high-level output	RESIN			25°C			20		
<b>.</b>			RESET	$V_{IH} = 2.7 \text{ V},$ $V_{IL} = 0.4 \text{ V},$ SENSE = $V_{IT+}$ max + 0.2 V,	Full range			24	μs	
<sup>t</sup> PLH				CONTROL = 0.4 V,	25°C			45		
			RESET	CT = NC <sup>†</sup>	Full range			65	ns	
			l		25°C			40		
t	Propagation delay time, high-to-low-level	RESIN	RESET	V <sub>IH</sub> = 2.7 V, V <sub>IL</sub> = 0.4 V, SENSE = V <sub>IT+</sub> max + 0.2 V,	Full range			60	ns	
<sup>t</sup> PHL	output	RESIN		CONTROL = 0.4 V, CT = NC†	25°C			20		
			RESET		Full range			24	μs	
	Propagation delay				25°C			38		
<sup>t</sup> PLH	time, low-to-high-level output	CONTROL	RESET	$V_{IH} = 2.7 \text{ V},$ $V_{IL} = 0.4 \text{ V},$ <u>SENSE</u> = $V_{IT+}$ max + 0.2 V,	Full range			58	ns	
	Propagation delay	CONTROL	KLOLI	RESIN = 2.7 V,	25°C			38		
<sup>t</sup> PHL	time, high-to-low-level output			CT = NC <sup>†</sup>	Full range			58	ns	
	Low-level minimum	SENSE		$V_{IH} = V_{IT+} max + 0.2 V,$ $V_{IL} = V_{IT-} min - 0.2 V,$	Full	3				
	pulse duration	RESIN		V <sub>IL</sub> = 0.4 V, V <sub>IH</sub> = 2.7 V	range	1			μs	
t <sub>r</sub>	Rise time		RESET	10% to 90%	Full		8			
t <sub>f</sub>	Fall time		and RESET	90% to 10%	range		4		ns/V	

<sup>†</sup> NC = No capacitor, and includes up to 100-pF probe and jig capacitance.



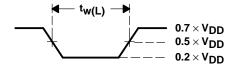
#### PARAMETER MEASUREMENT INFORMATION



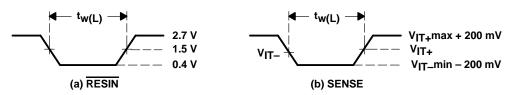
NOTES: A. For switching characteristics,  $R_L = 2 \ k\Omega$ . B.  $C_L = 50 \ pF$  includes jig and probe capacitance.

Figure 1. RESET AND RESET Output Configurations

#### I, Q, and Y suffixed devices

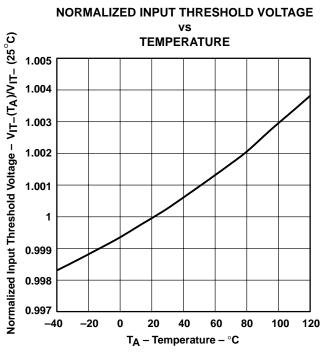


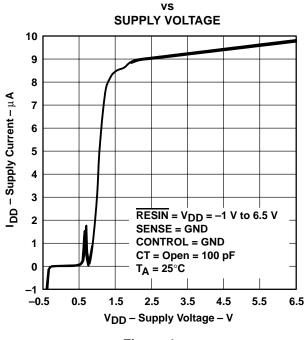
#### M suffixed devices



**Figure 2. Input Pulse Definition Waveforms** 

#### TYPICAL CHARACTERISTICS

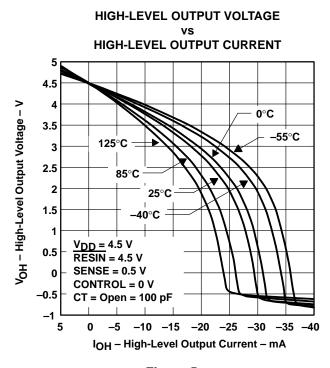




**SUPPLY CURRENT** 

Figure 3

Figure 4



**LOW-LEVEL OUTPUT VOLTAGE LOW-LEVEL OUTPUT CURRENT** V<sub>DD</sub> = 4.5 V RESIN = 4.5 V 5 SENSE = 5 V VoL - Low-Level Output Voltage - V CONTROL = 0 V CT = Open = 100 pF 125°C 3 85°C 25°C -40°C -55°C 5 0 10 15 20 25 30 -5 IOL - Low-Level Output Current - mA

Figure 5

Figure 6



#### **TYPICAL CHARACTERISTICS**

#### INPUT CURRENT vs INPUT VOLTAGE AT SENSE

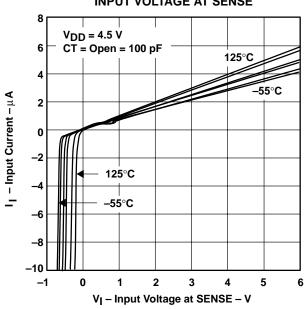


Figure 7

## MINIMUM PULSE DURATION AT SENSE

## SENSE THRESHOLD OVERDRIVE

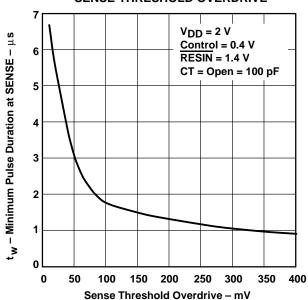


Figure 8



#### **APPLICATION INFORMATION**

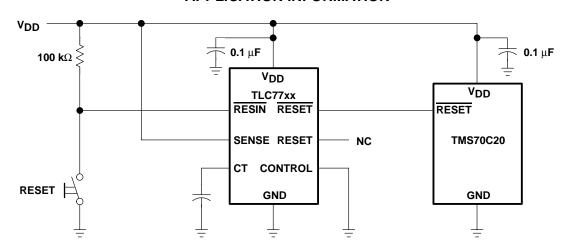


Figure 9. Reset Controller in a Microcomputer System

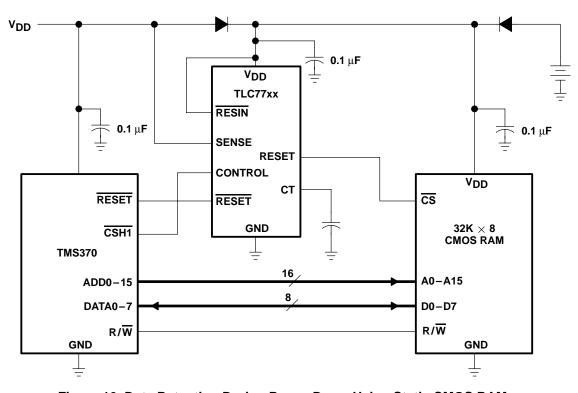


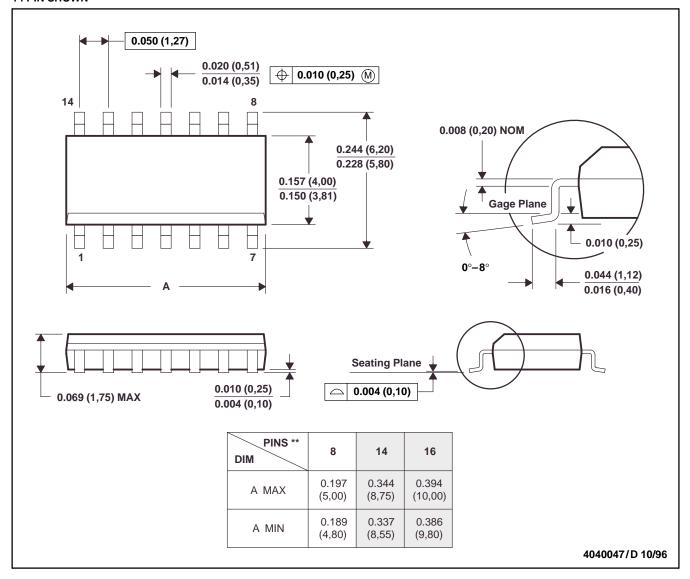
Figure 10. Data Retention During Power Down Using Static CMOS RAMs

#### **MECHANICAL DATA**

#### D (R-PDSO-G\*\*)

#### 14 PIN SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

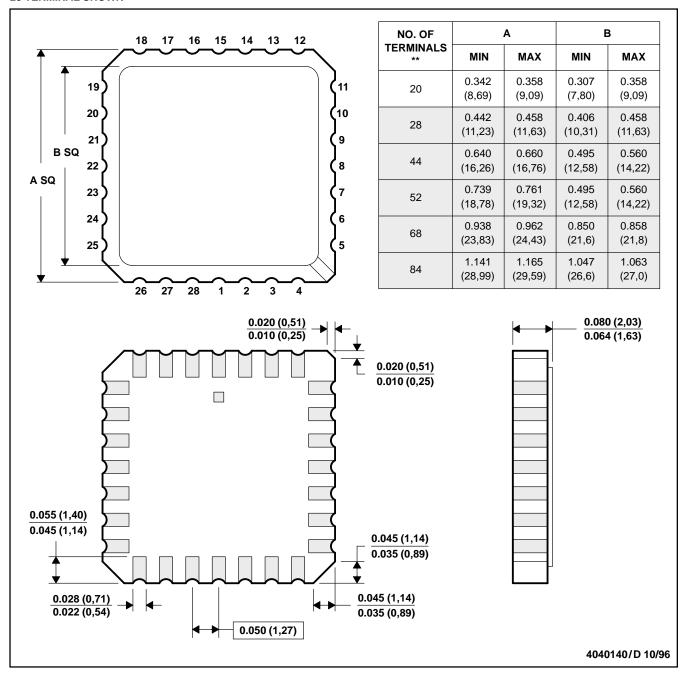
D. Falls within JEDEC MS-012

#### **MECHANICAL DATA**

#### FK (S-CQCC-N\*\*)

#### 28 TERMINAL SHOWN

#### LEADLESS CERAMIC CHIP CARRIER



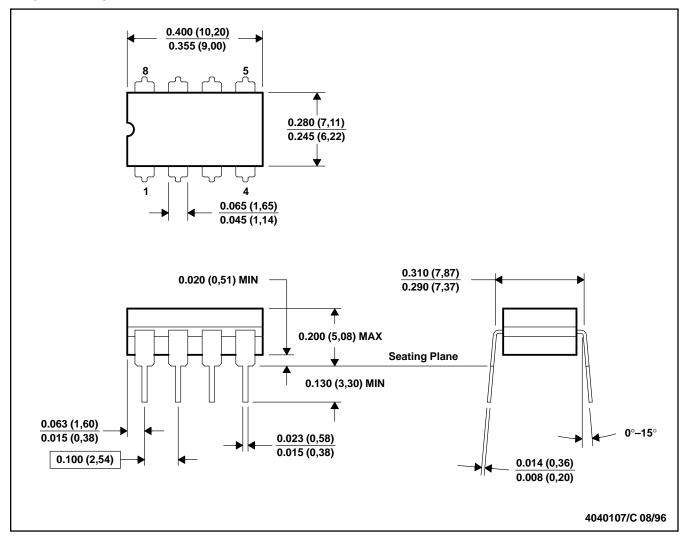
- NOTES: A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals are gold plated.
  - E. Falls within JEDEC MS-004



#### **MECHANICAL DATA**

#### JG (R-GDIP-T8)

#### **CERAMIC DUAL-IN-LINE PACKAGE**



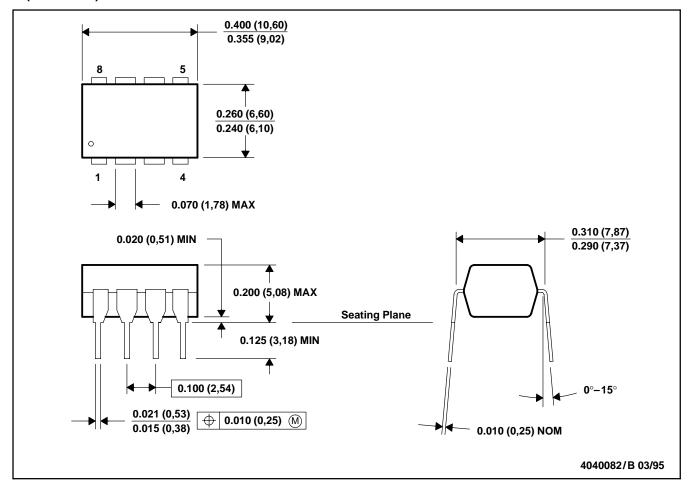
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL-STD-1835 GDIP1-T8

#### **MECHANICAL DATA**

#### P (R-PDIP-T8)

#### PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

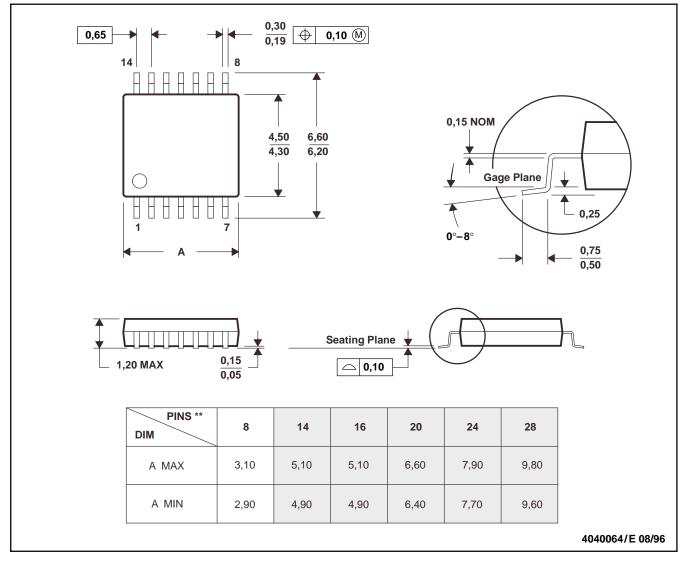
C. Falls within JEDEC MS-001

#### **MECHANICAL DATA**

#### PW (R-PDSO-G\*\*)

#### 14 PIN SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

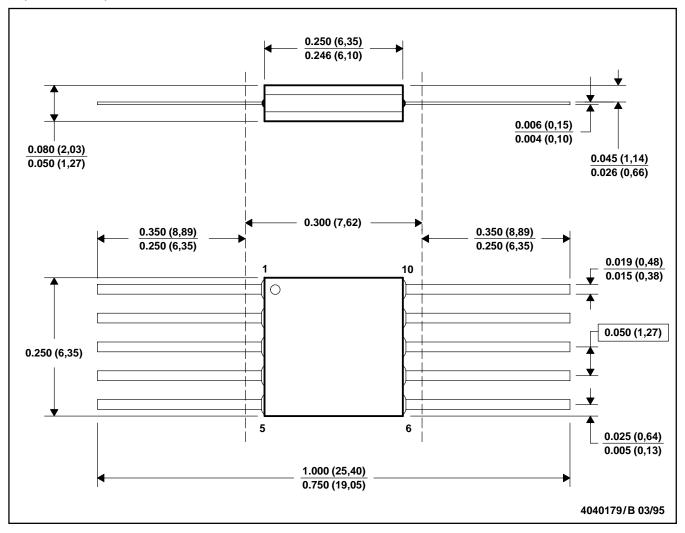
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

#### **MECHANICAL DATA**

#### U (S-GDFP-F10)

#### **CERAMIC DUAL FLATPACK**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F10 and JEDEC MO-092AA

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